

IN THE SPECIFICATION

Please replace the paragraph at page 1, line 25 to page 2, line 4, with the following rewritten paragraph:

Also, Japanese Patent Application Laid-Open No. ~~4-192474~~ 11-31208 (referred to as Second Patent Document) discloses a structure for preventing unauthorized reading of the circuit pattern provided on a semiconductor chip, where a plurality of recesses are formed on the back of the semiconducting chip so that the semiconductor chip easily breaks when subjected to unauthorized reading.

Please replace the paragraph at page 18, lines 19-22, with the following rewritten paragraph:

On the semiconductor wafer WF2 of Fig. 18, the vertical dicing lines ~~DL2~~ DL1 extend over the stripe-shaped recesses 90 and therefore cut thinner portions, but the semiconductor substrate 1 will not warp while being diced because both sides of the recesses 90 form the thick peripheral regions ~~4A~~ 5A as mentioned earlier.

Please replace the paragraph at page 22, lines 5-9, with the following rewritten paragraph:

Fig. 26 shows an example of plan view of the semiconductor substrate 8 seen from the second main surface side. As shown in the plan view of Fig. 26, the recesses 9D are shaped in stripes, where a plurality of stripe-shaped recesses 9D are arranged in parallel in the main surface of the semiconductor substrate 8. In Fig. 26, a cross-section cut across the plurality of recesses 9D corresponds to the sectional structure of Fig. ~~26~~ 25.

Atty. Docket No. 257478US2PCT

Inv: Norifumi TOKUDA, et al.

Preliminary Amendment filed w/new application

Please delete the original Abstract at page 42, lines 1-15 in its entirety and insert therefor the following substitute Abstract on a separate sheet as follows: